

CLAIMS

What is claimed is:

<sup>SUB
A1</sup> 1. A method for sequencing a developer process to reduce wafer pattern defects, comprising:

5 dispensing a substantially inert material onto a wafer surface prior to dispensing developer fluid.

2. A method for sequencing a developer process to reduce wafer pattern defects, comprising:

10 inducing a flow of developer fluid across a portion of a wafer surface for a time interval greater than a transit time for a fluid element to reach an outer wafer edge, the time interval prior to the substantial completion of the developing chemical reaction.

3. A method for sequencing a developer process to reduce wafer pattern defects, comprising:

15 dispensing a fresh charge of developer fluid over the wafer after a developing chemical reaction has proceed substantially to completion.

<sup>SUB
B2</sup> 4. The method of claim 3 further comprising:
dispensing a substantially inert material over a wafer subsequent to dispensing the fresh charge of developer fluid.

20

<sup>Add
B3</sup>

005270 2742960